This document can handle board shapes up to 7.6cm x 10cm, although our panel vendors top out at 7cm x 10cm.

To re-size the board shape, do the following:
- Select lines on the board outline and delete (stay in sample layer mode...above).
- Draw a rectangle using lines (example will be for a 6 x 6 board)
  - Enter Pline Line mode (keyboard p1)
  - Keyboard j1 to jump to 0,0, hit enter
  - Keyboard j1 to jump to location, set x to 0,000, hit enter twice
  - Keyboard j1 to jump to location, set x to 0,000 and y to 0,000, hit enter twice
  - Hit ES1 twice to exit Pline line mode

Select lines on the board outline:
- Menu DesignBoard Shape/Define from Selected Objects (keyboard d1)
- To delete a shape that mirrors the board outline:
  - Menu DesignBoard Shape/Define Primitive from Board Shape (keyboard d1)
  - Set the keep-out layer as the layer, set width as preferred
  - Ensure Polyline Tool Outline is selected, hit enter.

If you resize the board, don't forget to move the drill table strings on the Drill Drilling Layer...they should be just to the right of your board shape.
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